



Title: Flip chip interconnection structure

Inventor: Rajendra D. Pendse
Appln. No. 09/802,664

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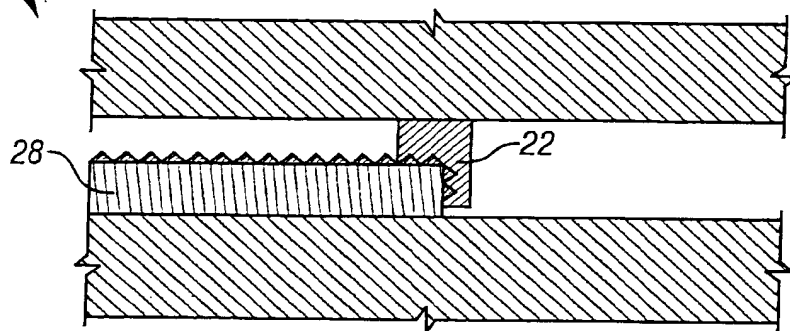


FIG. 2B

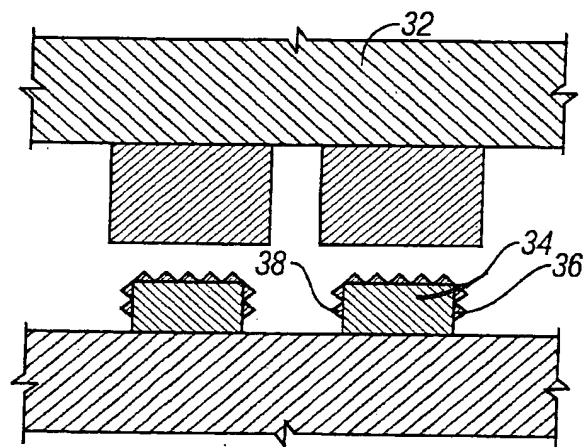


FIG. 3A

(move
lead line 34)

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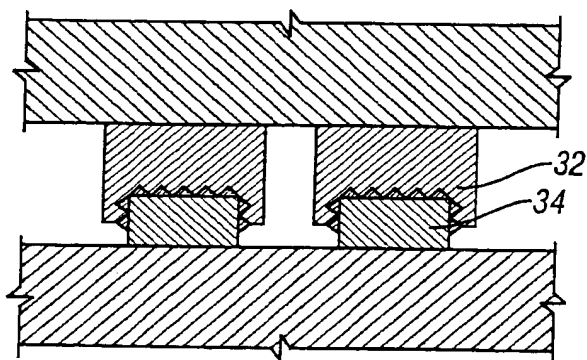


FIG. 3B



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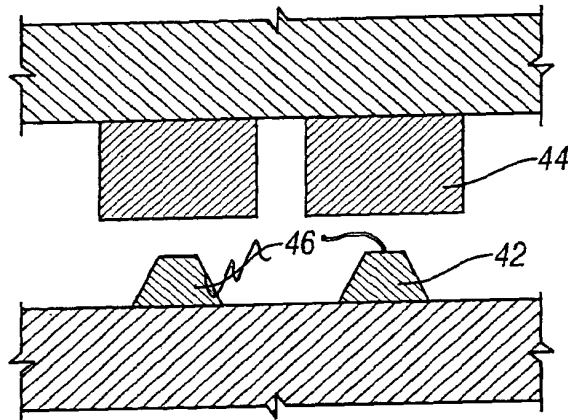


FIG. 4A

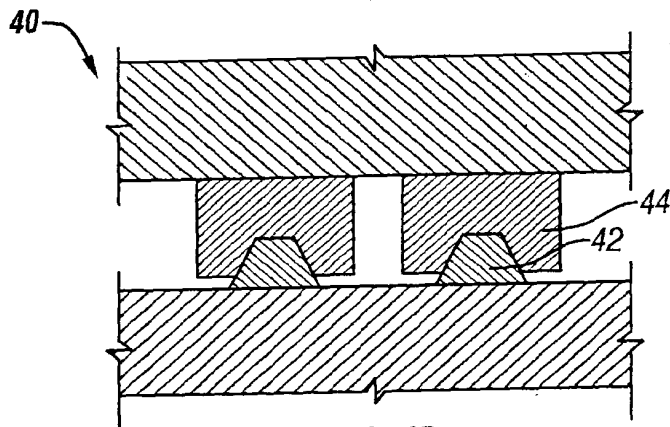


FIG. 4B

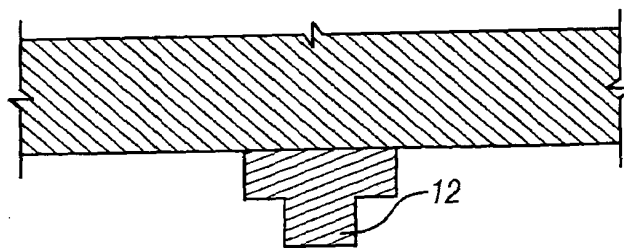


FIG. 5

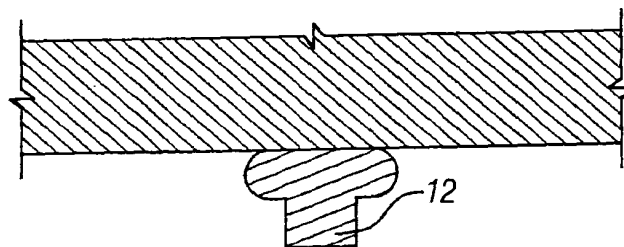


FIG. 6

(move lead line 46)



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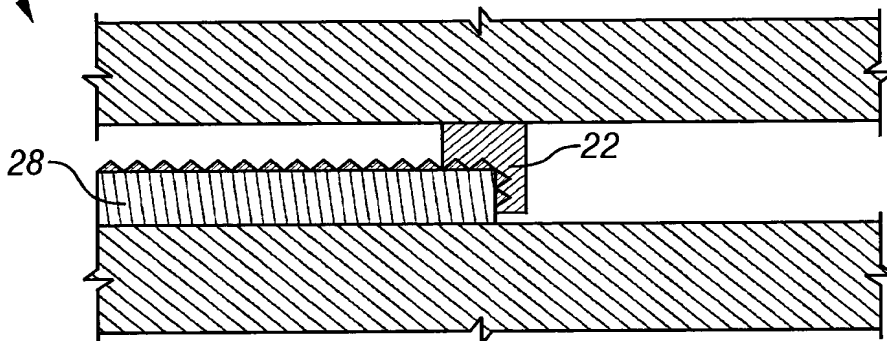


FIG. 2B

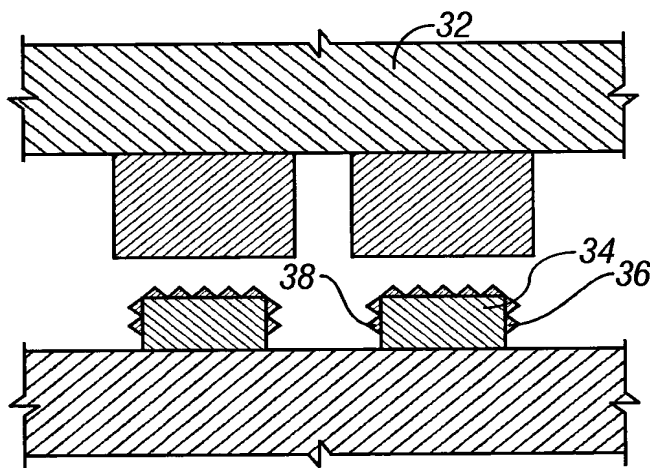


FIG. 3A

30

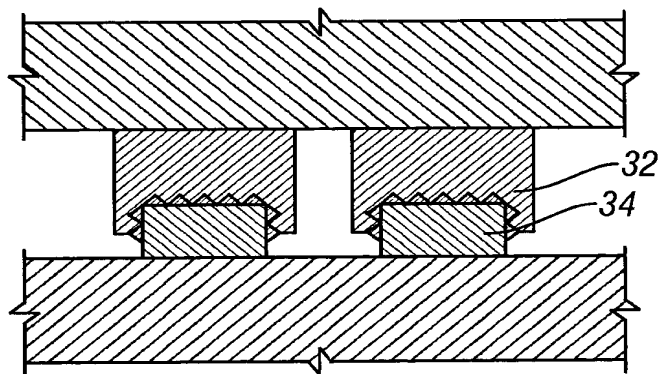


FIG. 3B



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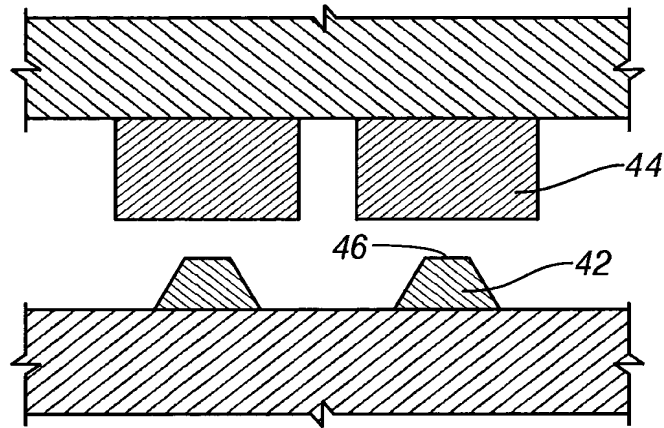


FIG. 4A

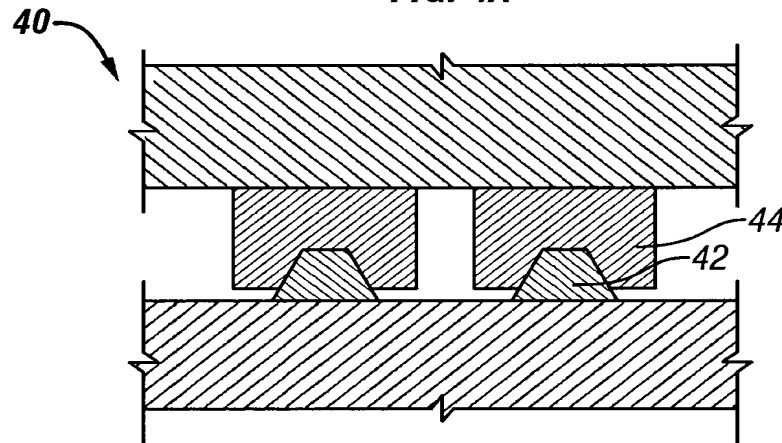


FIG. 4B

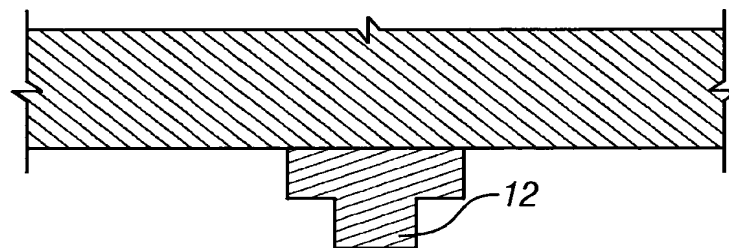


FIG. 5

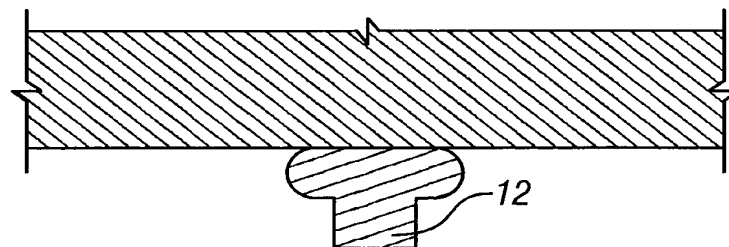


FIG. 6